

ABSTRACT OF THE DISCLOSURE

HEAT RESISTANT RESIN COMPOSITION, HEAT RESISTANT FILM ADHESIVE AND PROCESS FOR PRODUCING THE SAME

A heat resistant resin composition comprising, as the main components,

- (A) 100 parts by weight of an organic solvent-soluble polyimide resin having a glass transition temperature of 350°C or less,
- (B) 5 to 100 parts by weight of an epoxy compound having at least two epoxy groups in one molecule, and
- (C) 0.1 to 20 parts by weight of a compound having an active hydrogen group which can react with the epoxy compound (B),

a heat resistant film adhesive comprising, as the main components, the above components (A), (B) and (C), and a process for producing a heat resistant film adhesive by casting a solution of the above heat resistant resin composition on one side or both sides of a support.